高導熱玻纖布 HP Series

K=1.5~3.5 > 3.5 KV

El.italia serie IMFH-1500/2000/3500

High Thermal Conductivity Fiberglass Reinforcement

特 色 Characteristic

低熱阻抗 Low Thermal Contact Resistance.
導熱優，可低壓力應用 Exceptional Thermal Performance At Lower Application Pressures (20psi ~ 400psi).
適溫範圍大 Usable Over a Wide Temperature Range.
施工簡單、減少作業成本
Simplified Processing and Reduced Operating Costs.

適用範圍 Usage

IC, CPU, GPU, MOS, LED, M/B, PSU, PS, Heat Sink, LCD-TV, CASE, NB, PC, HDD, DDR Module, DVD, etc.

物 性 Properties	HP1500	HP2000	HP3500	Unit	Test Method
強化物-基材 Reinforcement	Fiberglass	Fiberglass	Fiberglass	—	—
厚 度 Thickness	0.2~0.5	0.2~0.5	0.2	mm	ASTM D374
比 重 Specific Gravity	2.4	2.7	2.9	g/cm^3	ASTM D792
硬 度 Hardness	80	75	80	Shore A	ASTM D2240
熱 阻 Thermal Impedance	0.48	0.28	0.2	℃-in^2/W	ASTM D5470
導熱係數 Thermal Conductivity	1.5	2.2	3.5	W/mk	HOT DISK
體積抗阻 Volume Resistivity	$>10^{13}$	$>10^{13}$	$>10^{13}$	Ωcm	ASTM D257
耐電壓值 Breakdown Voltage	> 3.5	> 3.5	> 3.5	KV	ASTM D149
介電常數 Dielectric Constant	6	7	8	1	ASTM D150
溫度範圍 Application temperature	-50 to 220	-50 to 220	-50 to 220	℃	—
抗拉強度 Tensile strength	> 300	> 300	> 300	psi	ASTM D412
延展率 Elongation	< 10	< 10	< 10	%	ASTM D412